# CL74LVC2G07 Dual Buffer and Driver With Open-Drain Outputs

## General Description

This dual buffer and driver is designed for 1.65-V to5.5-V VCC operation.

The output of the CL74LVC2G07 device is open drain and can be connected to other open-drain outputs to implement active-high wired-OR or active-high wired-AND functions. The maximum sink current is 32 mA.

## Ordering Information

| Part Number | Package | |
|---|---|---|
| CL74LVC2G07 | SOT-23-6<br>SOT-25<br>SOT-353<br>SOT-553 | |

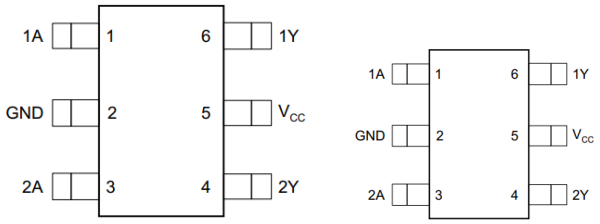
## Features

- Dual Open-Drain Buffer Configuration
- -24-mA Output Drive at 3.3 V
- Support Translation-Up and Down
- Supports 5-V Vcc Operation
- Inputs and Open-Drain Outputs Accept Voltages up to 5.5V
- Max Tpd of 3.7 ns at 3.3 V
- Low Power Consumption, 10-μA Max $I_{CC}$
- Typical $V_{OLP}$(Output Ground Bounce)<0.8V at Vcc = 3.3V, $T_A$ = 25℃
- Typical VOHV(Output VOH Undershoot)>2V at Vcc = 3.3V, TA = 25℃
- Ioff Supports Live Insertion, Partial-Power-Down-Mode, and Back-Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

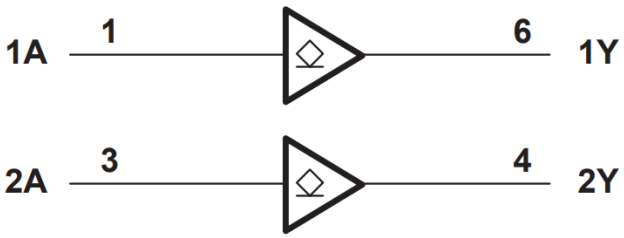
## Applications

- Blu-ray Player and Home Theater
- DVD Recorders and Players
- Desktop or Notebook PCs
- Digital Video Cameras (DVC)
- Embedded PC
- GPS: Personal Navigation Devices
- Mobile Phones
- Network Projector Front-Ends
- Portable Media Players
- Solid State Drive (SSD): Enterprise
- High-Definition (HDTV)
- Tablet: Enterprise
- Audio Dock: Portable
- DLP Front Projection Systems

## Pin Configuration




## Simplified Schematic



## Pin Assignment

| Pin Name | Pin No. | Pin Function |
|---|---|---|
| GND | 2 | Ground |
| 1A | 1 | Input 1 |
| 2A | 3 | Input 2 |
| 1Y | 6 | Open-drain output 1 |
| 2Y | 4 | Open-drain output 2 |
| Vcc | 5 | Power pin |

## Absolute Maximum Ratings (Note1)

- $V_{CC}$ ---------- -0.5V to +6.5V
- $V_I$ ---------- -0.5V to +6.5V
- $V_O$ (Voltage range applied to any output in the high-impedance or power-off state) ---------- -0.5V to +6.5V
- $V_O$ (Voltage range applied to any output in the high or slow state) ---------- -0.5V to +6.5V
- Input clamp current ---------- -50mA
- Output clamp current ---------- -50mA
- Continuous output current ---------- ±50mA
- Storage Temperature ---------- –65°C to 150°C

## Recommended Operating Conditions

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| Supply voltage | $V_{CC}$ | Operating | 1.65 | | 5.5 | V |
| | | Data retention only | 1.5 | | | |
| Input voltage | $V_I$ | | 0 | | 5.5 | V |
| Output voltage | $V_O$ | | 0 | | 5.5 | V |
| High- level input voltage | $V_{IH}$ | $V_{CC}$ = 1.65V to 1.95V | 0.65 x $V_{CC}$ | | | V |
| | | $V_{CC}$ = 2.3V to 2.7V | 1.7 | | | |
| | | $V_{CC}$ = 3V to 3.6V | 2 | | | |
| | | $V_{CC}$ = 4.5V to 5.5V | 0.7 x $V_{CC}$ | | | |
| Low- level input voltage | $V_{IL}$ | $V_{CC}$ = 1.65V to 1.95V | | | 0.35 x $V_{CC}$ | V |
| | | $V_{CC}$ = 2.3V to 2.7V | | | 0.7 | |
| | | $V_{CC}$ = 3V to 3.6V | | | 0.8 | |

| | | | | | | |
|---|---|---|---|---|---|---|
| | | $V_{CC}$ = 4.5V to 5.5V | | | 0.3 x $V_{CC}$ | |
| Low- level output current | $I_{OL}$ | $V_{CC}$ = 1.65V | | | 4 | mA |
| | | $V_{CC}$ = 2.3V | | | 8 | |
| | | $V_{CC}$ = 3V | | | 16 | |
| | | $V_{CC}$ = 3V | | | 24 | |
| | | $V_{CC}$ = 4.5V | | | 32 | |
| Input transition rise or fall rate | △T/△V | $V_{CC}$ = 1.8V±0.15V, 2.5V±0.2V | | | 20 | ns/V |
| | | $V_{CC}$ = 3.3V±0.3V | | | 10 | |
| | | $V_{CC}$ = 5V±0.5V | | | 5 | |
| Operating temperature | $T_A$ | | -40 | | 125 | ℃ |

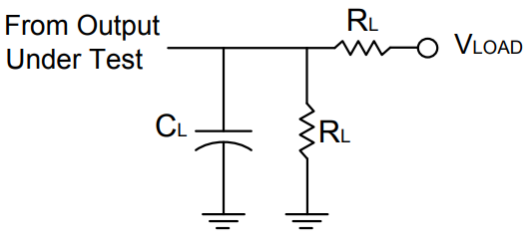
## Electrical Characteristics

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| Low- level output voltage | $V_{OL}$ | $V_{CC}$ = 1.65~5.5V, $I_{OL}$= 100uA | | | 0.1 | V |
| | | $V_{CC}$ = 1.65V, $I_{OL}$= 4mA | | | 0.45 | |
| | | $V_{CC}$ = 2.3V, $I_{OL}$= 8mA | | | 0.3 | |
| | | $V_{CC}$ = 3V, $I_{OL}$= 16mA | | | 0.4 | |
| | | $V_{CC}$ = 3V, $I_{OL}$= 24mA | | | 0.55 | |
| | | $V_{CC}$ = 4.5V, $I_{OL}$= 32mA | | | 0.55 | |
| Input leakage current | $I_I$ | $V_{IN}$= 5.5V or GND, $V_{CC}$= 0~5.5V | | | ±5 | uA |
| Power off leakage current | $I_{OFF}$ | $V_I$ or $V_O$ = 5.5V, $V_{CC}$=0V | | | ±10 | uA |
| Supply current | $I_{CC}$ | $V_{IN}$= $V_{CC}$ or GND, $I_{OUT}$=0, $V_{CC}$=1.65~5.5V | | | 10 | uA |
| Additional supply current per input pin | $\triangle I_{CC}$ | $V_{CC}$=3~5.5V, one input ate $V_{CC}$-0.6V, other input at $V_{CC}$ or GND | | | 500 | uA |

## Switching Characteristics

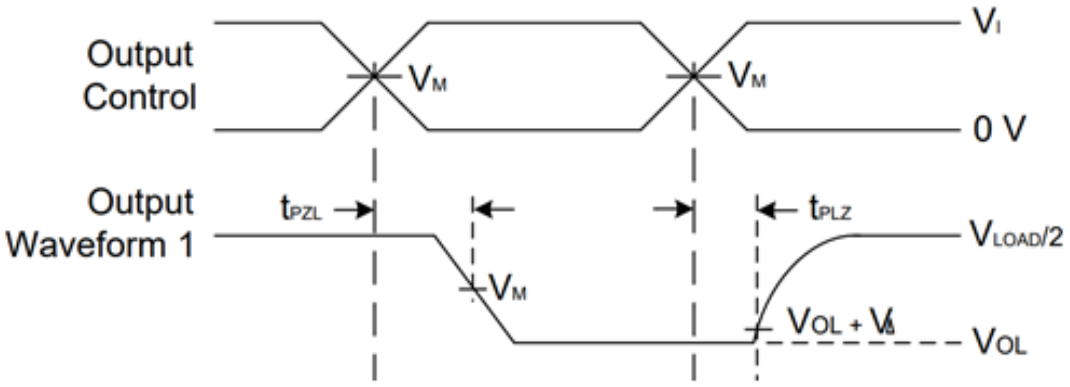
| Parameter | Symbol | Test Conditions | | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|---|
| Propagation delay from input(A or B) to output(Y) | $T_{PD}$ | $V_{CC}$ = 1.8V±0.15V, $R_L$=1KΩ | $C_L$=30pF | 1.5 | | 8.6 | ns |
| | | $V_{CC}$ = 2.5V±0.2V , $R_L$=500Ω | | 1 | | 4.4 | |
| | | $V_{CC}$ = 3.3V±0.3V, $R_L$=500Ω | $C_L$=50pF | 1 | | 3.7 | |
| | | $V_{CC}$ = 5V±0.5V, $R_L$=500Ω | | 1 | | 2.9 | |

## Parameter Measurement Information




| TEST | Condition |
|---|---|
| $t_{PLZ}$ | $V_{LOAD}$ |
| $t_{PZL}$ | $V_{LOAD}$ |

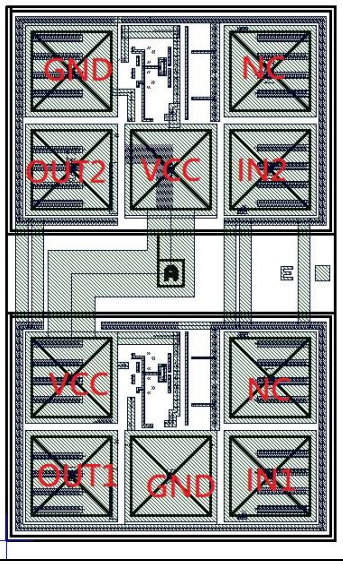
| VCC | INPUTS | | $V_M$ | $V_{LOAD}$ | $C_L$ | $R_L$ | $V_\triangle$ |
|---|---|---|---|---|---|---|---|
| | $V_I$ | $t_r/t_f$ | | | | | |
| 1.8V ± 0.15V | $V_{CC}$ | ≦2ns | $V_{CC}/2$ | 2 X $V_{CC}$ | 30pF | 1kΩ | 0.15V |
| 2.5V ± 0.2V | $V_{CC}$ | ≦2ns | $V_{CC}/2$ | 2 X $V_{CC}$ | 30pF | 500Ω | 0.15V |
| 3.3V ± 0.3V | 3V | ≦2.5ns | 1.5V | 6V | 50pF | 500Ω | 0.3V |
| 5V ± 0.5V | $V_{CC}$ | ≦2.5ns | $V_{CC}/2$ | 2 X $V_{CC}$ | 50pF | 500Ω | 0.3V |




**Voltage Waveform Enable and DisableTimes**
**Low- and High-Level Enabling**

Notes:
A. $C_L$ includes probe and jig capacitance
B. All pulses and supplied at pulse repetition rate≦10MHz
C. The Inputs are measured one at a time with one transition per measurement
D. For the open drain device $t_{PLZ}$ and $t_{PZL}$ are the same as $t_{PD}$
E. $t_{PZL}$ is measured at $V_M$
F. $t_{PLZ}$ is measured at $V_{OL}$ + $V_\triangle$

## PAD Location and Coordinates

| PHYSICAL CHARACTERISTICS | | UNIT | CHIP DRAWING |
|---|---|---|---|
| Wafer Size | 200 | mm |  |
| Die Size (with S/L) | 0.308 * 0.466 | $mm^2$ | |
| Scribe line width | 60 | um | |
| TOP Metal thickness | 3 | µm | |
| Top Metallization | Al-Cu | | |
| Wafer Thickness | 726 | µm | |
| CUP (circuit under PAD) or not | YES | | |
| Bonding Wire Diameter | 20 | um | |



| PAD NAME | PAD SIZE (µm²) | Coordinate |
|---|---|---|
| IN2 | 60*60 | (199,282) |
| GND | 60*60 | (49,357) |
| GND | 60*60 | (124,49) |
| IN1 | 60*60 | (199,49) |
| OUT1 | 60*60 | (49,49) |
| VCC | 60*60 | (49,124) |
| OUT2 | 60*60 | (49,282) |

## Bonding Diagram Example